ABSTRACT OF THE DISCLOSURE

SUBSTRATE TREATING APPARATUS AND METHOD

Provided are a substrate treating apparatus and method, which vacuum-absorb a substrate. An inner space of a housing is maintained at a second pressure by a pipe maintained at a first pressure. The interior of a vacuum hole of a vacuum chuck is maintained at a third pressure. A substrate is vacuum-absorbed by a difference between the third pressure and the second pressure. A gas is supplied into a first line connected to the vacuum hole, or the first line communicates with the inner space of the housing to maintain the difference between the third pressure and the second pressure within a previously set range, thereby to unload the substrate. Therefore, the absorption between the substrate and the vacuum chuck can be increased, and also, a process speed can be improved.

Fig. 1

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